FIGURE 24. Die photo of testing device (left) and dummy device (right).
4.3 Test set-up

The die photo of the LNA is shown in Fig. 34. The die was mounted on a PCB using conductive epoxy for proper backside contact. Both input and output matching networks, as shown in Fig. 35, were implemented by microstrip lines.

FIGURE 34. Die photo of the single-ended LNA. Input at left and output at right.

FIGURE 35. The impedance matching networks implemented by microstrip lines.
FIGURE 36. The LNA mounted on PCB.

FIGURE 37. Through microstrip line used to de-embed the loss due to connecting line.